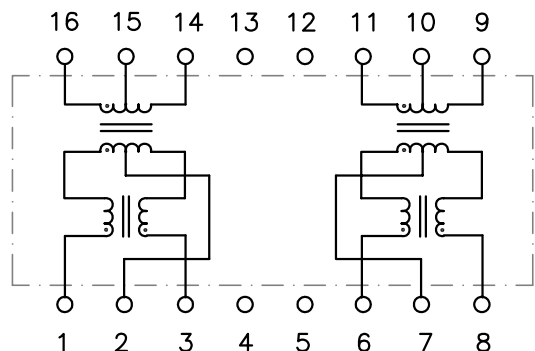


**PART NO. : TG110-ESV01N6RL**



16PIN FAST ETHERNET ISOLATION MODULE  
 RoHS COMPLIANT  
 COMPATIBLE TO LEAD-FREE SOLDERING PROCESS  
 CONDITION PER IPC/JEDEC J-STD-020C  
 UL/EU60950 AND DEMKO RECOGNIZED  
 ENHANCED SHOCK/VIBRATION PERFORMANCE  
 EXTENDED OPERATING TEMPERATURE -40/+85°C  
 STORAGE TEMPERATURE -57/+125°C



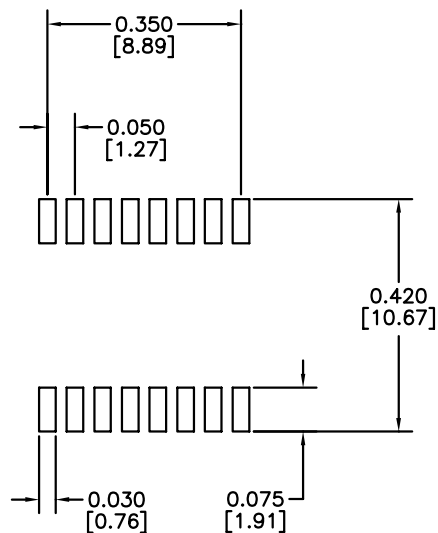
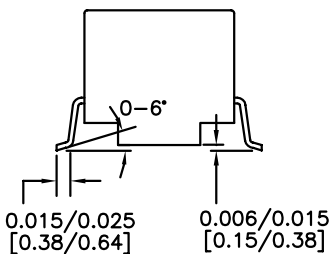
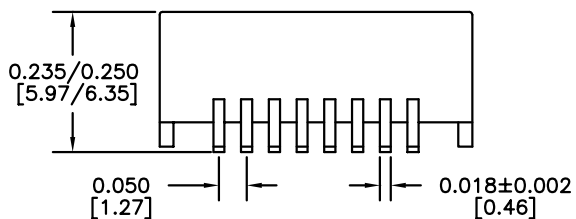
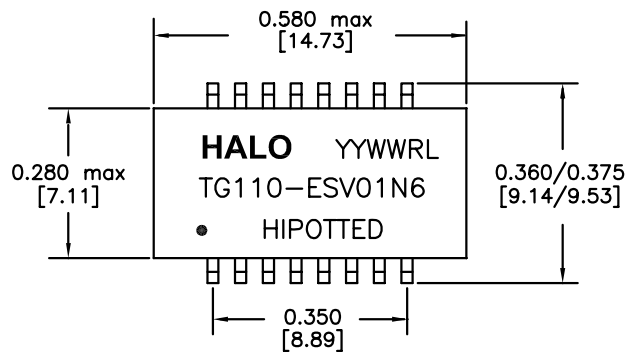
**ELECTRICAL SPECIFICATIONS @25° C**

TURNS RATIO P1-3:P16-14 P6-8:P11-9 OCL (100KHz,0.1Vrms,8mA) P16-14,P11-9 DCR P16-14,P11-9 LL P16-14,P11-9 Cw/w INSERTION LOSS 0.1-100MHz RETURN LOSS 0.5-30MHz 40MHz 50MHz 60-80MHz TYPICAL CROSSTALK 0.1-100MHz TYPICAL CMR 0.1-30MHz 40-100MHz ISOLATION	1CT:1CT ±3% 1CT:1CT ±3% 350µH min* 1.0Ω max 0.4µH max 40pF max -1.1dB max -18dB min -15.5dB min -13.6dB min -12dB min -40dB min -60dB min -50dB min 1,500Vrms
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\* MINIMUM OCL OVER OPERATING TEMPERATURE



<b>HALO/PBL</b>	TITLE ISOLATION MODULE		SIGNATURES		DATE	REV.	DESC.	DATE
	FOR FAST ETHERNET		DRAWN	PETER LU	11/5/04	A	FIRST ISSUE	11/5/04
CALIFORNIA, USA KOWLOON, HONG KONG SINGAPORE	PART NO. TG110-ESV01N6RL		CHECKED	LEI KEONG	1/31/08	B	PROD. RELEASE	1/31/08
	SCALE NONE	PAGE 1 OF 2	APPROVED	PETER LU	1/31/08			
			FILE	ESV01N6RL.DWG				



CO-PLANARITY: 0.004 [0.10]  
 DIMENSIONS: Inch [mm]  
 TOLERANCES: ±0.005 INCH IF NOT SPECIFIED

RECOMMENDED SOLDER PAD DIMENSIONS

**HALO/PBL**

CALIFORNIA, USA  
 KOWLOON, HONG KONG  
 SINGAPORE

TITLE	ISOLATION MODULE		SIGNATURES	DATE	REV.	DESC.	DATE
FOR	FAST ETHERNET		DRAWN	PETER LU	11/5/04	A	FIRST ISSUE
PART NO.	TG110-ESV01N6RL		CHECKED	LEI KEONG	1/31/08	B	PROD. RELEASE
SCALE	NONE	PAGE	2 OF 2	APPROVED	PETER LU	1/31/08	
				FILE	ESV01N6RL.DWG		